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Total No. of Questions: 18

B.Tech. (ECE) (Sem.-3)
ELECTRONIC DEVICES
Subject Code: UC-BTEC-301-19
M.Code: 78746

Time: 3 Hrs. Max. Marks: 60

INSTRUCTIONS TO CANDIDATES:

- SECTION-A is COMPULSORY consisting of TEN questions carrying TWO marks each.
- 2. SECTION-B contains FIVE questions carrying FIVE marks each and students have to attempt any FOUR questions.
- 3. SECTION-C contains THREE questions carrying TEN marks each and students have to attempt any TWO questions.

SECTION-A

Write briefly:

- 1) How can you classify solids on the basis of conductivity? Give examples also.
- 2) Give the Energy band diagrams of Intrinsic and Extrinsic Semiconductors.
- 3) Differentiate between Drift current and Diffusion current in a semiconductor.
- 4) What do you understand by:
 - i) Depletion region and
 - ii) Potential barrier in a semiconductor.
- 5) What is Ebers-Moll model in Transistors?
- 6) Define MOSFET. Give its types.
- 7) What is the purpose of Sputtering in Fabrication process of ICs or devices?
- 8) Give the circuit symbols for Zener diode, Tunnel diode, Varactor diode and a Transistor. Label them properly.
- 9) Draw the Input and Output V-I characteristics of a bipolar junction transistor. Label the characteristics wherever required.
- 10) What is the significance of Etching in fabrication processes of Electronics devices? Name some commonly used etchants.

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SECTION-B

- 11) Discuss the behavior of pn-junction diode when forward biased as well as reverse biased giving suitable neat diagrams.
- 12) Explain the construction and working of a MOSFET. Give its V-I characteristics.
- 13) What are the three important configurations in which the transistor can be connected? Discuss any one of them.
- 14) Define: Diffusion and Ion-Implantation. What are the various types of Ion-implantation techniques that are commonly used in fab line?
- 15) A full-wave rectifier uses two diodes, the internal resistance of each diode may be assumed constant at 20Ω . The transformer r.m.s. secondary voltage from centre tap to each end of secondary is 50V and load resistance is 980V. Find:
 - i) The mean load current (Idc)
 - ii) The r.m.s. value of load current

SECTION-C

- 16) Draw and explain Half-wave and full-wave (center-tapped & bridge) rectifiers with suitable circuit diagrams. Which one is more preferable and why?
- 17) Write short notes on:
 - i) Light Emitting Diode (LED)
 - ii) Schottky Diode.
- 18) List and explain the various important fabrication processes used for the fabrication of BJTs/MOSFETs.

NOTE: Disclosure of Identity by writing Mobile No. or Making of passing request on any page of Answer Sheet will lead to UMC against the Student.

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